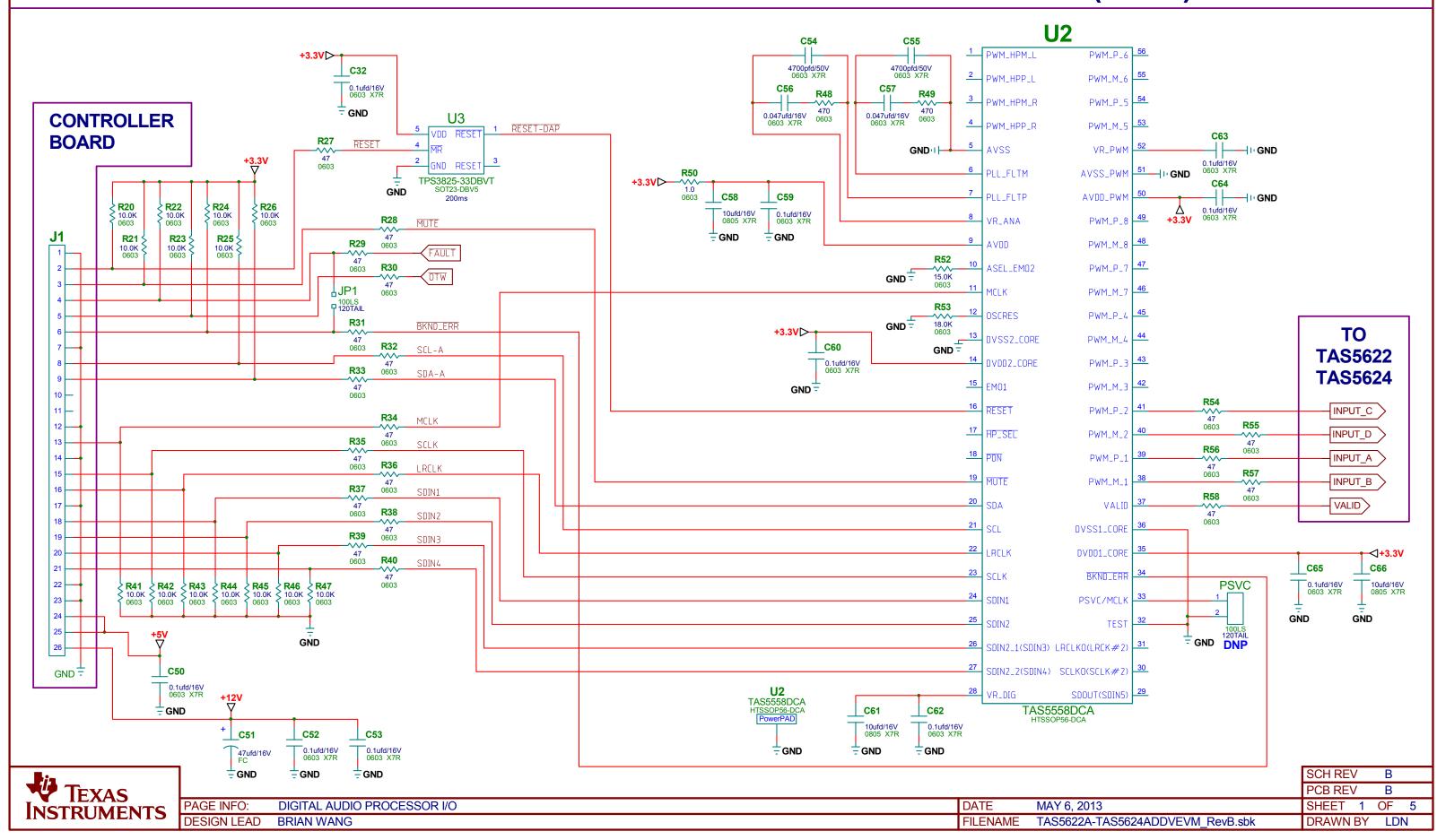
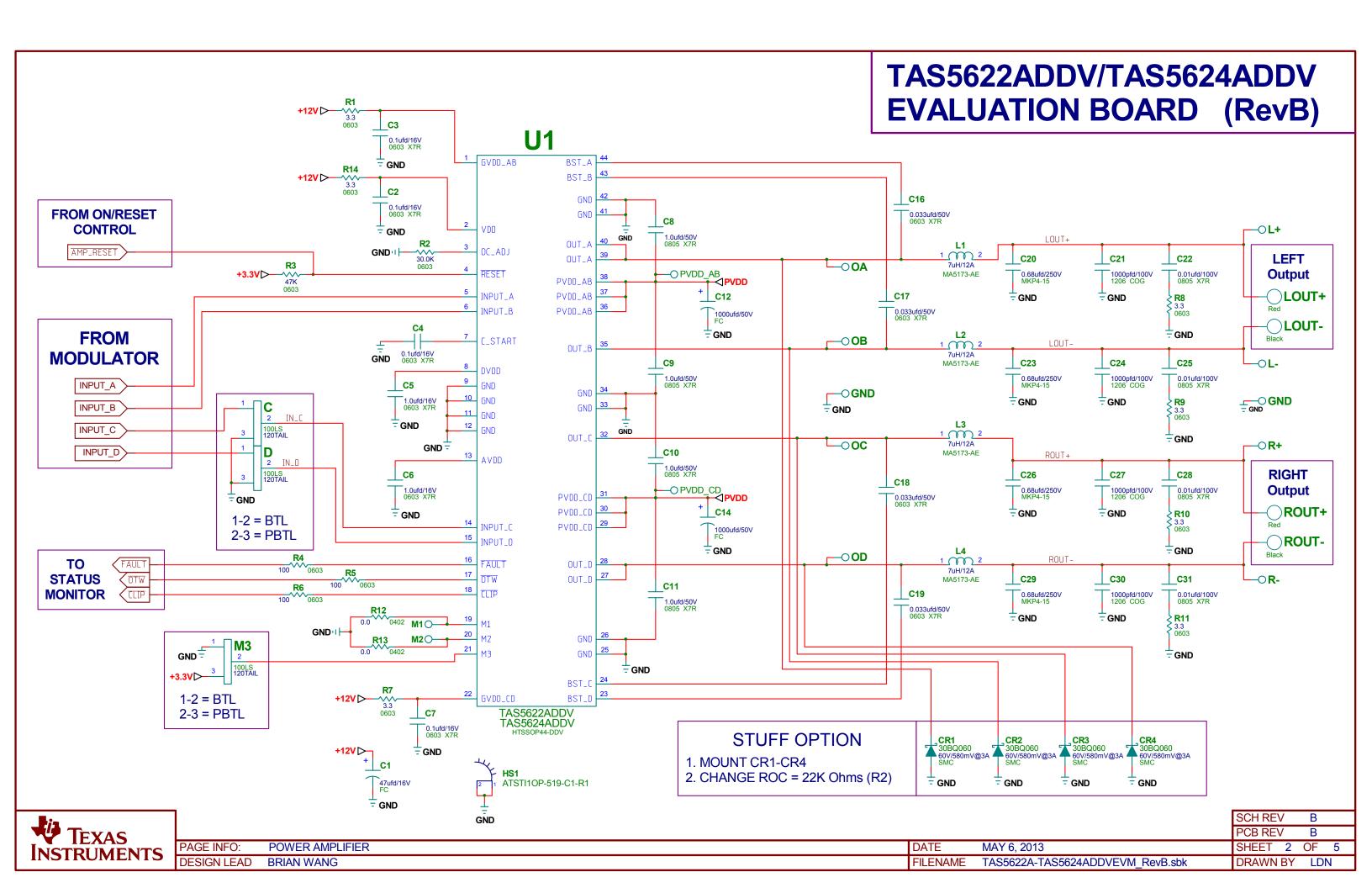
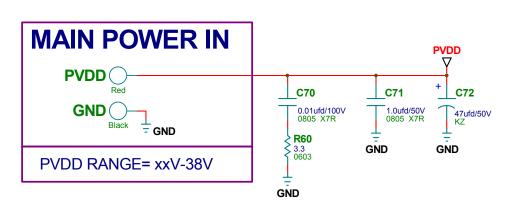
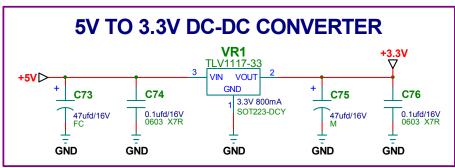
TAS5622ADDV/TAS5624ADDV EVALUATION BOARD (RevB)

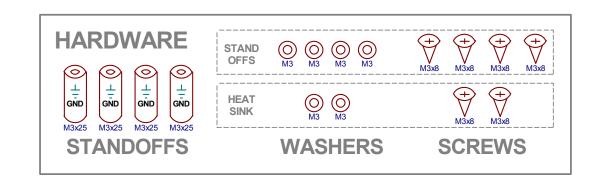


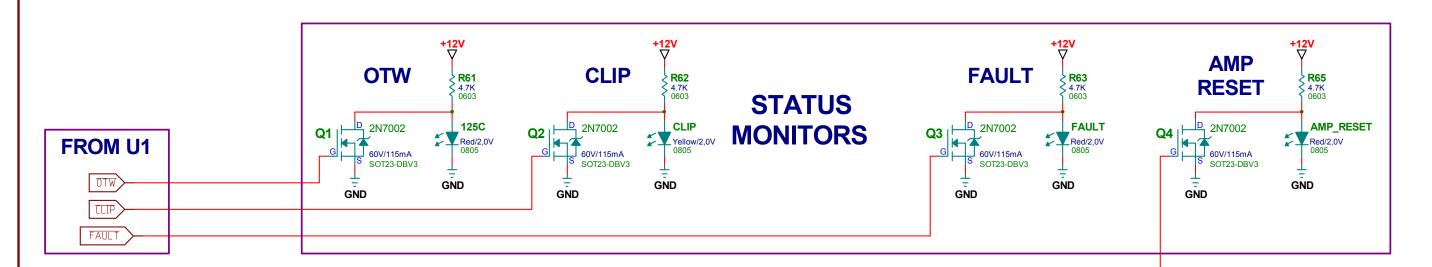


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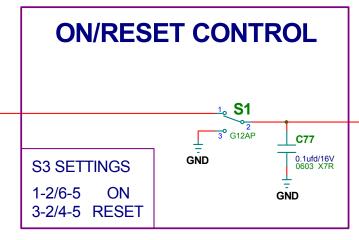












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SCH REV B
PCB REV B
SHEET 3 OF 5
DRAWN BY LDN

PAGE INFO: POWER SUPPLY, STATUS MONITORS, ON/OFF CONTROL
DESIGN LEAD BRIAN WANG

DATE MAY 6, 2013

NAME TAS5622A-TAS5624ADDVEVM_RevB.sbk

TAS5622ADDV/TAS5624ADDV EVALUATION BOARD (RevB)

REVISION HISTORY					
REVISION	DESCRIPTION	DATE	APPROVAL		
Α	INITIAL RELEASE	MARCH 7, 2012	sc		
В	 CHANGE U2 FROM TAS5548DGG TO TAS5558DCA. DELETED ET2. SHORTED ACROSS AND DELETED R51. CHANGED HEATSINK TO MODEL 519. 	MAY 6, 2013	BW		

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PAGE INFO:

DESIGN LEAD BRIAN WANG

REVISION HISTORY

SCH REV	В	
PCB REV	В	
SHEET 4	OF	5
DRAWN BY	LDN	

MAY 6, 2013

FILENAME TAS5622A-TAS5624ADDVEVM_RevB.sbk

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